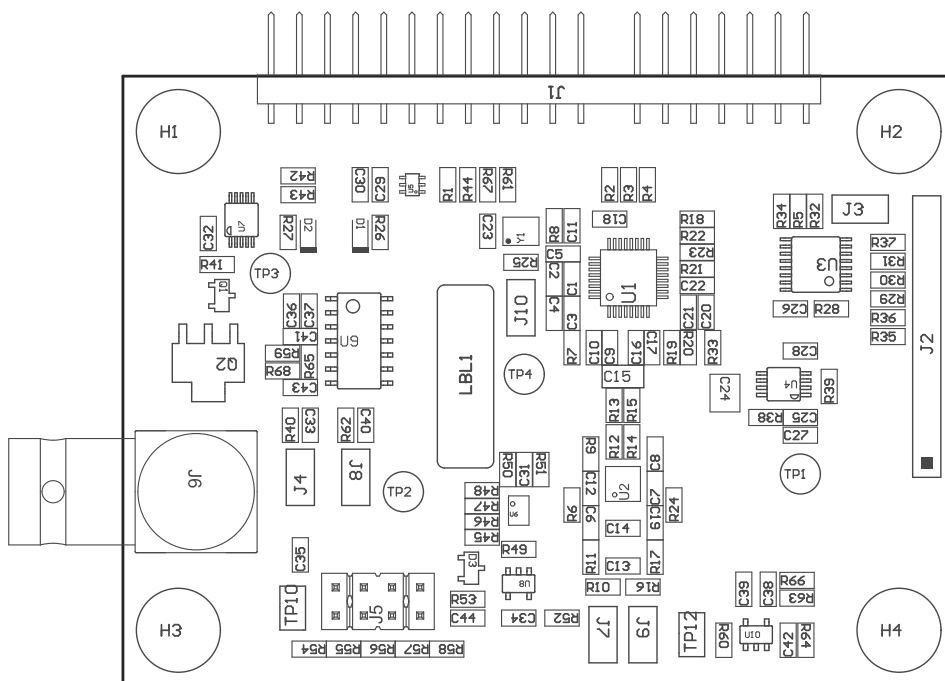


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01471	REV: E2	SUN REV: Not In VersionControl
	TID #: TIDA-01471		
PLOT NAME = Top Assembly Drawing	GENERATED : 6/21/2017	2:12:58 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01471	REV: E2	SUN REV: Not In VersionControl
	TID #: TIDA-01471		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/21/2017 2:13:00 PM	TEXAS INSTRUMENTS	

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